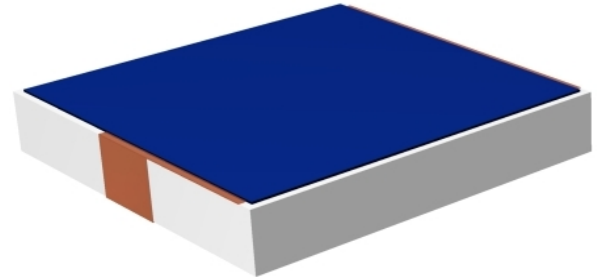


FEATURES

- Low Profile Surface Mount
- High Power
- Aluminum Nitride Substrate
- Low VSWR
- Ideal For Automated Assembly

APPLICATIONS

- Mobile Networks
- Broadcast
- High Power Amplifiers
- Instrumentation
- Isolators
- Military
- Satellite Communications



GENERAL DESCRIPTION

EMC Technology's surface mount terminations are designed for direct installation on printed circuit boards and manufactured using thick film technology. Edge metallization on two sides forms the solder fillets for stronger attachment, easier inspection, and increased heat removal area. The devices are available in Alumina, Aluminum Nitride or Beryllium Oxide.

SPECIFICATIONS

1.0 ELECTRICAL

- Nominal Impedance: 50 Ω
- Frequency Range: DC – 4.0 GHz
- VSWR: DC 2.7 GHz 1.13:1 Max
2.7 – 4.0 GHz 1.20:1 MAX
- Temperature Coefficient: ± 200 PPM/ $^{\circ}$ C Max
- Power Rating: 150 Watts
- Operating Temperature: -55 $^{\circ}$ C To +150 $^{\circ}$ C
- DC Resistance: 50 Ω \pm 2%

2.0 MECHANICAL

- Substrate: Aluminum Nitride
- Resistive Film: Thick Film
- Metallization: Thick Film, Silver Plated

3.0 UNIT MARKING

None

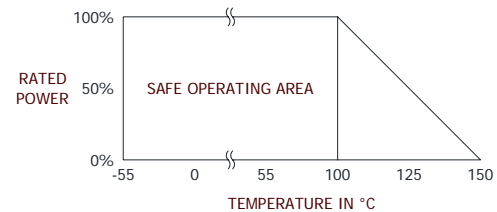
4.0 PACKAGING

- Standard: Tape and Reel
- Optional: Available Upon Request

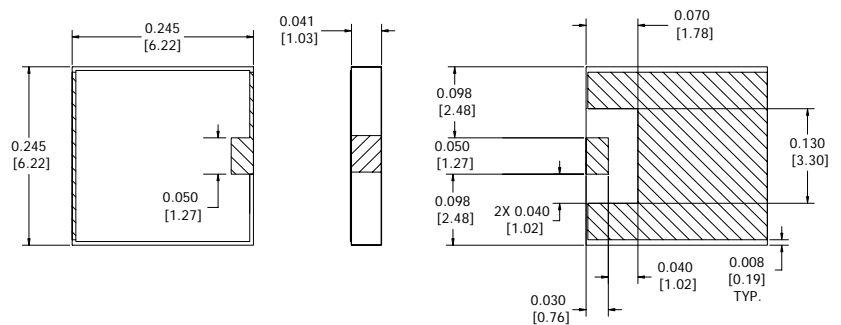
5.0 PART NUMBERING

- Part Identifier: SMT252503ALN2F

POWER RATING AND DERATING



MECHANICAL OUTLINE



Note: Specifications are subject to change without notice.

TOLERANCE: \pm .010